



SHEET 1 OF 1

LIST OF ART CITED BY APPLICANT
(PTO-1449)

ATTY. DOCKET NO.
IK-0073

APPLN. SERIAL NO.
10/786,308

APPLICANT(S)

Ye-Yong KIM

FILING DATE

February 26, 2004

GROUP

3744

U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	*PATENT NO.	*ISSUE DATE	*INVENTOR NAME	CLASS	SUBCLASS	FILING DATE
CJ	6,351,382 B1	02-2002	Nakanishi et al.	361	700	
OJ	6,400,565 B1	06-2002	Shabbir et al.	361	687	
OJ	6,166,908	12-2000	Samaras et al.	361	700	
OJ	6,328,097 B1	12-2001	Bookhardt et al.	165	104.33	

U.S. PATENT APPLICATION PUBLICATIONS

	*PATENT APPLN. PUB. NO.	*PUB. DATE	*APPLICANT	CLASS	SUBCLASS	
OJ	2002/0167799 A1	11-2002	Kawashima et al.	361	700	
OJ	2003/0016500 A1	01-2003	Malone et al.	361	701	

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	*APPLN. NO.	*FILING DATE	*INVENTOR	CLASS	SUBCLASS	

FOREIGN PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
OJ	CN2515800	10/9/02	China (Full reference)				X

OTHER ART (Including Author, Title, Date, Pertinent Pages, Publisher, Place of Publication, Etc.)

OJ	David A. Reay, Heat Pipe, in AccessScience@McGraw-Hill, http://www.accessscience.com , DOI 10.1036/1097-8542.757297, May 13, 2002
OJ	Charles A. Harper, Cooling with Heat Pipes, Electronic packaging & Interconnection Handbook, pages 2.79-2.80, McGraw Hill, 1997

EXAMINER

CJ

DATE CONSIDERED

4/7/06

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP§909; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.
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